

# Package Style/Part Number Reference



Package Style	Packaging Part Number Suffix	Package Style	Packaging Part Number Suffix
Ceramic Surface Mount Package	-A2	SSOP-8	-62
Chip/Wafer	-000	5 Lead Ceramic Package	-65
SOT-23	-001	SOT-5	-72
SOT-23	-003	SOT-6	-73
SOT-23	-004	PFP-16 with Slug (7 x 7 mm)	-75
SOT-23	-005	12 Lead Metal Package	-77
SOT-23	-006	20 Lead Metal Package	-78
SOT-23	-007	SSOP-16 with Slug	-79
7 Lead Ceramic Package	-01	SSOP-16	-80
SOD-323	-011	SOIC-8 with Slug	-84
SOT-143	-015	SSOP-20	-85
SOT-143	-016	MSOP-10	-86
SOT-143	-017	TSSOP-16	-87
SOT-143	-019	SSOP-16 Exposed Pad	-89
SOT-143	-020	SC-88 (6 Lead SC-70)	-92
SOT-143	-021	Chip on Board	-93
SOT-143	-022	TSSOP-16 Exposed Pad	-93
SOT-143	-023	TSSOP-20 Exposed Pad	-94
SOT-143	-026	Single Chip Microstrip Package	-99
SOT-5 Lead	-027	Chip on Board	-100
20 Lead Metal Package	-05	Chip on Board	-101
SC-70	-073	Chip on Board	-102
SC-70	-074	Chip on Board	-103
SC-70	-075	Chip on Board	-106
SC-70	-076	Ceramic Micro-X	-212
SC-79	-079	Ceramic Micro-X	-213
8 Lead Glass Package	-08	MLF-16 (4 x 4 mm) 1.7 mm Paddle	-300
7 Lead Ceramic Package	-10	LPCC-20 (4 x 4 mm) 1.7 mm Paddle	-301
8 Lead Glass Package	-11	MSOP-8 Exposed Pad	-302
SOIC-8	-12	MLF-16 (4 x 4 mm) 2.1 mm Paddle	-306
Multi Chip Microstrip Package	-14	LPCC-16 (4 x 4 mm) 2.8 mm Paddle	-307
SOIC-14	-24	MLF-20 (4 x 4 mm)	-308
SOIC-16	-25	MLF-32 (5 x 5 mm) 3.3 mm Paddle	-310
6 Lead Metal Package	-29	MLF-12 (3 x 3 mm)	-311
14 Lead Glass Package	-31	QFN-16 (4 x 4 x 1 mm) 1.47 mm Paddle	-317
SOT-143	-32	Thermally Enhance, Ultra Small Micro Lead Frame Package (3 x 3 x 0.75 mm)	-320
SOT-23	-39	LGA-6 (1.5 x 1.2 x 0.82 mm)	-334
6 Lead Metal Package	-53	QFN-6 (2 x 2 x 0.9 mm)	-335
8 Lead Ceramic Package	-54	SOIC-8 Exposed Pad (5.99 x 4.93 x 1.55 mm)	-339
9 Lead Metal Package	-57	QFN-20 (4 x 4 mm) 2.1 mm Paddle	-340
MSOP-8	-59	SOT-66 6 Lead (1.65 x 1.65 x 0.60 mm)	-344
8 Lead Ceramic Package	-60	LGA (1.44 x 1.20 x 0.70 mm)	-508
LQFP-32 (7 x 7 mm)	-61		